

Process and Device for Embossing

Abstract

The invention relates to a process for embossing a structure in an embossing material (4) applied on a substrate (1), with the following process steps, in particular the following sequence:

- Embossing the embossing material (4) by an embossing die (2),
- Hardening the embossing material (4),

characterized in that at least the substrate (1) and/or the embossing die (2) and/or at least one heating layer (3) arranged between the substrate (1) and the embossing material (4) and/or between the embossing die (2) and the embossing material (4) are at least at times irradiated by means of microwaves for hardening the embossing material (4).

In addition, this invention relates to a corresponding device.

In this regard, see Figure 2c.